

2.5 V/3.3 V Differential LVPECL 2x2 Clock Switch and Low Skew Fanout Buffer



ON Semiconductor®

www.onsemi.com

NB4L6254

Description

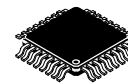
The NB4L6254 is a differential 2x2 clock switch and drives precisely aligned clock signals through its LVPECL fanout buffers. It employs a fully differential architecture with bipolar technology, offers superior digital signal characteristics, has very low clock output skew and supports clock frequencies from DC up to 3.0 GHz.

The NB4L6254 is designed for the most demanding, skew critical differential clock distribution systems. Typical applications for the NB4L6254 are clock distribution, switching and data loopback systems of high-performance computer, networking and telecommunication systems, as well as on-board clocking of OC-3, OC-12 and OC-48 communication systems. In addition, the NB4L6254 can be configured as a single 1:6 or dual 1:3 LVPECL fanout buffer.

The NB4L6254 can be operated from a single 3.3 V or 2.5 V power supply.

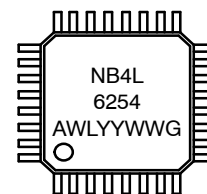
Features

- Maximum Clock Input Frequency, 3 GHz
- Maximum Input Data Rate, 3 Gb/s
- Differential LVPECL Inputs and Outputs
- Low Output Skew: 50 ps Maximum Output-to-Output Skew
- Synchronous Output Enable Eliminating Output Runt Pulse Generation and Metastability
- Operating Range: Single 3.3 V or 2.5 V Supply
 $V_{CC} = 2.375\text{ V to }3.465\text{ V}$
- LVC MOS Compatible Control Inputs
- Packaged in LQFP-32
- Fully Differential Architecture
- $-40^{\circ}\text{C to }85^{\circ}\text{C}$ Ambient Operating Temperature
- These are Pb-Free Devices*



LQFP-32
FA SUFFIX
CASE 561AB

MARKING DIAGRAM*



- A = Assembly Location
 - WL = Wafer Lot
 - YY = Year
 - WW = Work Week
 - G = Pb-Free Package
- (Note: Microdot may be in either location)

*For additional marking information, refer to Application Note [AND8002/D](#).

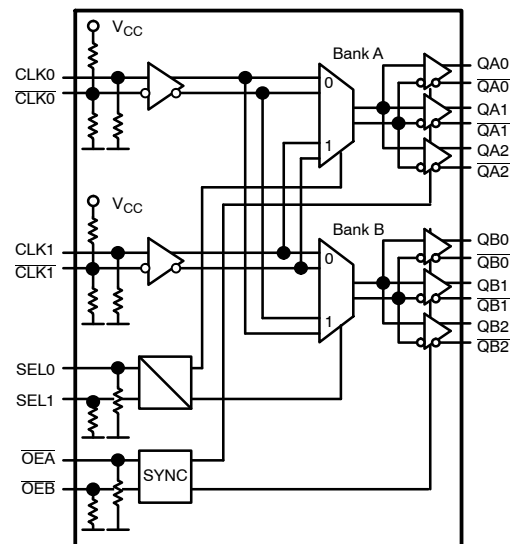


Figure 1. Functional Block Diagram

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, [SOLDERRM/D](#).

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

NB4L6254

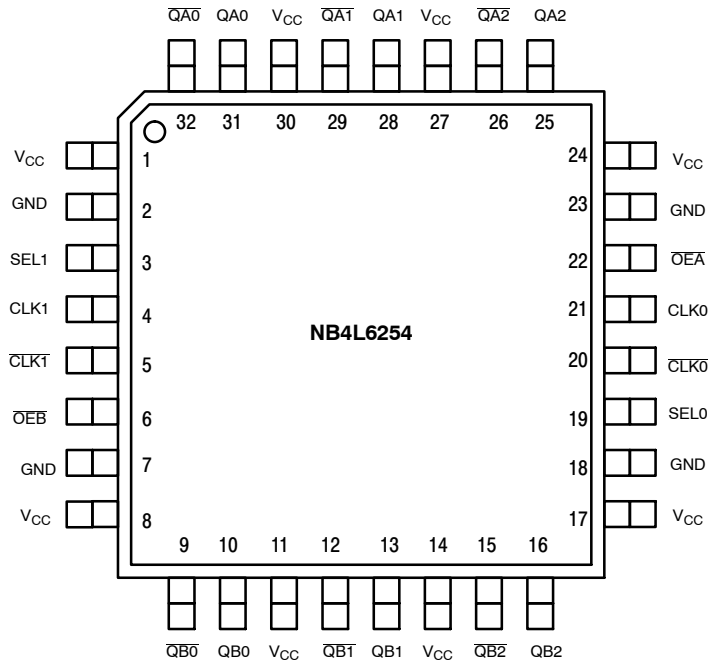


Figure 2. 32-Lead LQFP Pinout (Top View)

Table 1. PIN DESCRIPTION

Pin Name	I/O	Description
CLK0, $\overline{\text{CLK0}}$	LVPECL Input	Differential reference clock signal input 0.
CLK1, $\overline{\text{CLK1}}$	LVPECL Input	Differential reference clock signal input 1.
OEA, $\overline{\text{OEB}}$	LVC MOS Input	Output Enable
SEL0, SEL1	LVC MOS Input	Clock Switch Select
QA[0-2], $\overline{\text{QA}}[0-2]$ QB[0-2], $\overline{\text{QB}}[0-2]$	LVPECL Output	Differential LVPECL Clock Outputs, (banks A and B) Typically terminated with 50 Ω resistor to $V_{\text{CC}} - 2.0 \text{ V}$.
GND	Power Supply	Negative Supply Voltage
V_{CC}	Power Supply	Positive supply voltage. All V_{CC} pins must be connected to the positive power supply for correct DC and AC operation.

Table 2. FUNCTION TABLE

Control	Default	0	1
$\overline{\text{OEA}}$	0	QA[0-2], $\overline{\text{QA}}[0-2]$ are active. Deassertion of $\overline{\text{OEA}}$ can be asynchronous to the reference clock without generation of output runt pulses	QA[0-2] = L, $\overline{\text{QA}}[0-2]$ = H (outputs disabled). Assertion of $\overline{\text{OE}}$ can be asynchronous to the reference clock without generation of output runt pulses
$\overline{\text{OEB}}$	0	QB[0-2], $\overline{\text{QB}}[0-2]$ are active. Deassertion of $\overline{\text{OEB}}$ can be asynchronous to the reference clock without generation of output runt pulses	QB[0-2] = L, $\overline{\text{QB}}[0-2]$ = H (outputs disabled). Assertion of $\overline{\text{OE}}$ can be asynchronous to the reference clock without generation of output runt pulses
SEL0, SEL1	00	Refer to Table 3	Refer to Table 3

NB4L6254

Table 3. CLOCK SELECT CONTROL

SEL0	SEL1	CLK0 Routed To	CLK1 Routed to	Application Mode
0	0	QA[0:2] and QB[0:2]	–	1:6 Fanout of CLK0
0	1	–	QA[0:2] and QB[0:2]	1:6 Fanout of CLK1
1	0	QA[0:2]	QB[0:2]	Dual 1:3 Buffer
1	1	QB[0:2]	QA[0:2]	Dual 1:3 Buffer (Crossed)

Table 4. ATTRIBUTES

Characteristics	Value
Internal Input Pullup Resistor	37.5 kΩ
Internal Input Pulldown Resistor	75 kΩ
ESD Protection Human Body Model Machine Model	> 2000 V > 200 V
Latchup Immunity	> 200 mA
Cin, inputs	4.0 pF (TYP)
Moisture Sensitivity (Note 1) LQFP–32	Level 2
Flammability Rating Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in
Transistor Count	336
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

1. For additional information, see Application Note [AND8003/D](#).

Table 5. MAXIMUM RATINGS (Note 2)

Symbol	Parameter	Condition	Condition	Rating	Unit
V _{CC}	Positive Power Supply			$-0.3 \leq V_{CC} \leq 3.6$	V
V _{IN}	DC Input Voltage			$-0.3 \leq V_{IN} \leq V_{CC} + 0.3$	V
V _{OUT}	DC Output Voltage			$-0.3 \leq V_{OUT} \leq V_{CC} + 0.3$	V
I _{IN}	DC Input Current			±20	mA
I _{out}	LVPECL DC Output Current	Continuous Surge		±50 100	mA mA
T _A	Operating Temperature Range	LQFP–32		–40 to +85	°C
T _{stg}	Storage Temperature Range			–65 to +150	°C
θ _{JA}	Thermal Resistance (Junction–to–Ambient) (Note 3)	0 lfpm 500 lfpm	LQFP–32 LQFP–32	80 55	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction–to–Case)	2S2P (Note 3)	LQFP–32	12 to 17	°C/W
T _{sol}	Wave Solder Pb–Free			265	°C
V _{TT}	Output Termination Voltage			V _{CC} – 2.0, TYP	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Maximum Ratings are those values beyond which device damage may occur.

3. JEDEC standard multilayer board – 2S2P (2 signal, 2 power); MIL–SPEC 883E Method 1012.1.

NB4L6254

Table 6. DC CHARACTERISTICS $V_{CC} = 2.375 \text{ V to } 3.465 \text{ V}$, $GND = 0 \text{ V}$, $T_A = -40^\circ\text{C to } +85^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Unit
POWER SUPPLY CURRENT					
I_{GND}	Power Supply Current (Outputs Open)		60	85	mA
LVPECL CLOCK OUTPUTS					
V_{OH}	LVPECL Output HIGH Voltage (Notes 4, 5) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	$V_{CC} - 1145$ 2155 1355	$V_{CC} - 1020$ 2280 1480	$V_{CC} - 895$ 2405 1605	mV
V_{OL}	LVPECL Output LOW Voltage (Notes 4, 5) $V_{CC} = 3.3 \text{ V}$ $V_{CC} = 2.5 \text{ V}$	$V_{CC} - 1945$ 1355 555	$V_{CC} - 1770$ 1530 730	$V_{CC} - 1600$ 1700 900	mV
CLOCK INPUTS					
V_{PP}	Dynamic Differential Input Voltage (Clock Inputs)	0.1		1.3	V
V_{CMR}	Differential Cross-point Voltage (Clock Inputs)	1.0		$V_{CC} - 0.3$	V
LVC MOS CONTROL INPUTS					
V_{IH}	Output HIGH Voltage (LVTTTL/LVCMOS)	2.0			V
V_{IL}	Output LOW Voltage (LVTTTL/LVCMOS)			0.8	V
I_{IH}	Input Current $V_{IN} = V_{CC}$ or $V_{IN} = GND$	-100		+100	μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

- LVPECL Outputs loaded with 50Ω termination resistors to $V_{TT} = V_{CC} - 2.0 \text{ V}$ for proper operation.
- LVPECL Output parameters vary 1:1 with V_{CC} .

Table 7. AC CHARACTERISTICS $V_{CC} = 2.375 \text{ V to } 3.465 \text{ V}$, $GND = 0 \text{ V}$, $T_A = -40^\circ\text{C to } +85^\circ\text{C}$ (Note 6)

Symbol	Characteristic	Min	Typ	Max	Unit
V_{INPP}	Differential Input Voltage (Peak-to-Peak)	0.3		1.3	V
V_{CMR}	Differential Input Cross-Point Voltage (Clock Inputs)	1.2		$V_{CC} - 0.3$	V
f_{IN}	Clock Input Frequency	0		3.0	GHz
V_{OUTPP}	Differential Output Output Voltage Amplitude (Peak-to-Peak) (Note 7) $f_O < 1.1 \text{ GHz}$ $f_O < 2.5 \text{ GHz}$ $f_O < 3.0 \text{ GHz}$	0.45 0.35 0.2	0.70 0.55 0.35		V
f_{CLKOUT}	Output Clock Frequency Range	0		3.0	GHz
t_{pd}	Propagation Delay CLKx to Qx (Differential Configuration)	360	485	610	ps
t_{skew}	Within Device Output-to-Output Skew (Differential Configuration) Device-to-Device Skew Output Pulse Skew (Duty Cycle Skew) (Note 8)		25 30 10	50 250 60	ps
DCO	Output CLOCK Duty Cycle (DC Ref = 50%) (Note 9) $t_{REF} < 100 \text{ MHz}$ $t_{REF} < 800 \text{ MHz}$	49.4 45.2		50.6 54.8	%
t_{JIT}	CLOCK Random Jitter (RMS) (SEL0 \neq SEL1) (Note 10)		0.3	0.8	ps
t_r, t_f	Output Rise/Fall Times (Note 11) CLKx / $\overline{\text{CLKx}}$	50	130	300	ps
t_{PDL}	Output Disable Time, T = CLK period	$2.5 T + t_{PD}$		$3.5 T + t_{PD}$	ns
t_{PLD}	Output Enable Time, T = CLK period	$3 T + t_{PD}$		$4 T + t_{PD}$	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm.

- LVPECL Outputs loaded with 50Ω to $V_{CC} - 2.0 \text{ V}$.
- $V_{OUTPP} \text{ MIN} = 0.1 \text{ V}$ @ $+85^\circ\text{C}$, $f_O < 3.0 \text{ GHz}$.
- Output Pulse Skew is the absolute difference of the propagation delay times: $|t_{PLH} - t_{PHL}|$
- $\text{DCO}_{\text{MIN/MAX}} = 43.2\%/59.2\%$ @ $+85^\circ\text{C}$.
- $t_{JIT\text{MAX}} = 1.6 \text{ ps}$ @ 85°C , 3.0 V
- Measured 20% to 80%.

NB4L6254

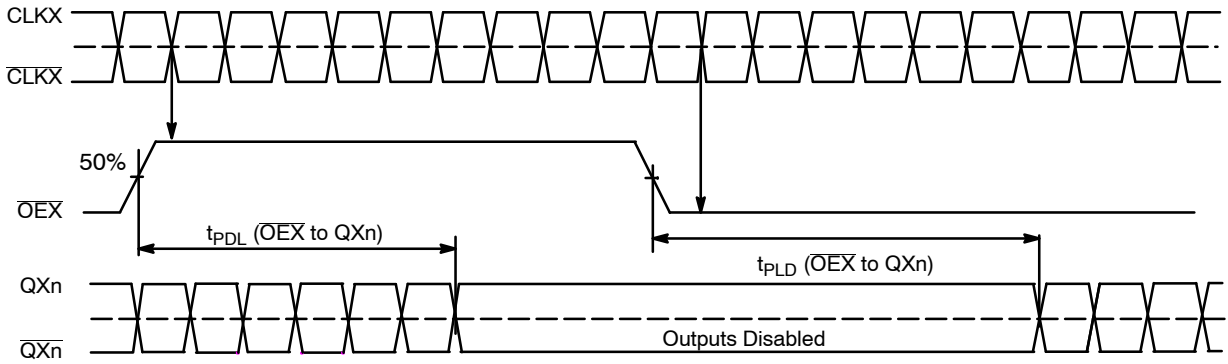


Figure 3. Output Disable / Enable Timing

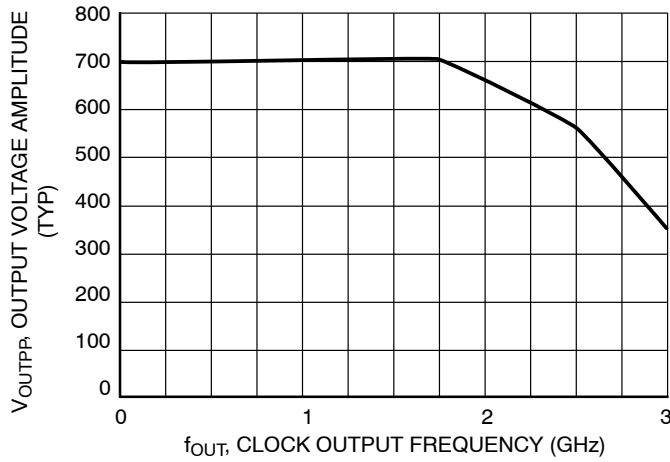


Figure 4. Output Voltage Amplitude (V_{OUTPP}) versus Clock Output Frequency at Ambient Temperature (Typical)

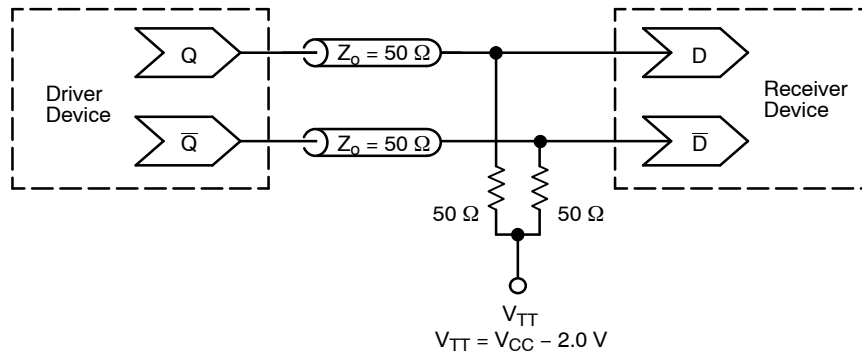


Figure 5. Typical Termination for Output Driver and Device Evaluation (See Application Note [AND8020/D](#) – Termination of ECL Logic Devices.)

Example Configurations

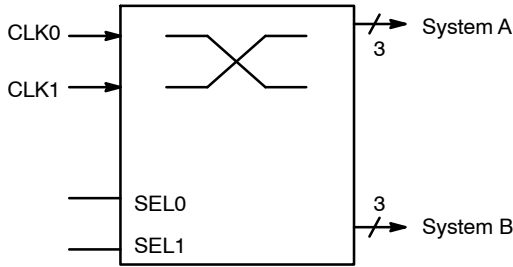


Figure 6. 2 x 2 Clock Switch

SEL0	SEL1	Switch Configuration
0	0	System Loopback
0	1	Line Loopback
1	0	Transmit/Receive Operation
1	1	System and Line Loopback

APPLICATIONS INFORMATION

Maintaining Lowest Device Skew

The NB4L6254 guarantees low output–output bank skew at 50 ps and a part–to–part skew of 250 ps. To ensure low skew clock signals in the application, both outputs of any differential output pair need to be terminated identically, even if only one output is used. When fewer than all nine output pairs are used, identical termination of all output pairs within the output bank is recommended. If an entire output bank is not used, it is recommended to leave all of these outputs open and unterminated. This will reduce the device power consumption while maintaining minimum output skew.

SEL0	SEL1	Switch Configuration
0	0	CLK0 Clocks System A and System B
0	1	CLK1 Clocks System A and System B
1	0	CLK0 Clocks System A and CLK1 Clocks System B
1	1	CLK1 Clocks System B and CLK1 Clocks System A

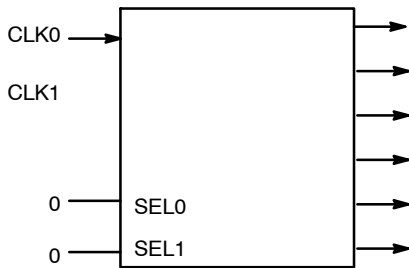


Figure 7. 1:6 Clock Fanout Buffer

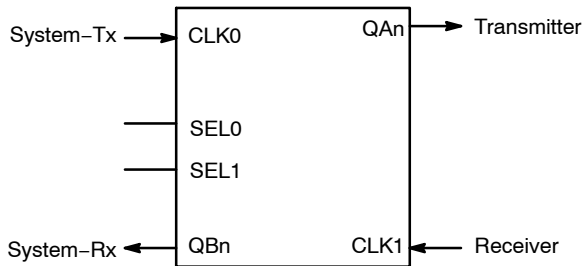


Figure 8. Loopback Device

Power Supply Bypassing

The NB4L6254 is a mixed analog/digital product. The differential architecture of the NB4L6254 supports low noise signal operation at high frequencies. In order to maintain its superior signal quality all V_{CC} pins should be bypassed by high–frequency ceramic capacitors connected to GND. If the spectral frequencies of the internally generated switching noise on the supply pins cross the series resonant port of an individual bypass capacitor, its overall impedance begins to look inductive and thus increases with increasing frequency. The parallel capacitor combination shown ensures that a low impedance path to ground exists for frequencies well above the noise bandwidth.

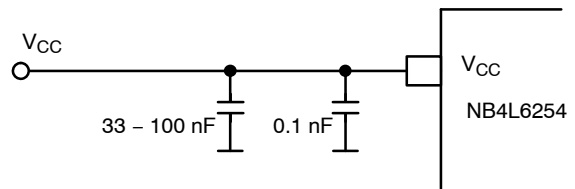


Figure 9. V_{CC} Power Supply Bypass

NB4L6254

ORDERING INFORMATION

Device	Package	Shipping [†]
NB4L6254FAR2G	LQFP-32 (Pb-Free)	2000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

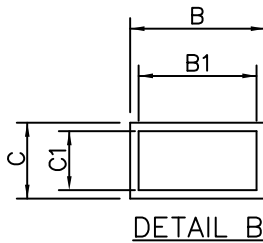


LQFP-32, 7x7
CASE 561AB-01
ISSUE O

DATE 19 JUN 2008



SYMBOL	MIN	NOM	MAX
A	—	—	1.60
A1	0.05	—	0.15
A2	1.35	1.40	1.45
B	0.30	0.37	0.45
B1	0.30	0.35	0.40
C	0.09	—	0.20
C1	0.09	—	0.16
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
e	0.80 BSC		
L	0.45	0.60	0.75
L1	1.00		
R1	0.08	—	0.20
α°	11	—	13
β°	0	—	7
γ°	0	—	—



ALL DIMENSIONS IN MM

DOCUMENT NUMBER:	98AON30893E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	32 LEAD LQFP, 7X7	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative